

MATERIAL DECLARATION SHEET



Material Number	CRM2010 Series (less than 1Ω)		
Product Line	High power lead free chip resistors		
Compliance Date	09/01/2016		
RoHS Compliant	Yes	MSL	N/A



No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	21.4686	Aluminum oxide	1344-28-1	96	83.688	87.175
				Silicon dioxide	14808-60-7	2	1.7435	
				Magnesium oxide	1309-48-4	2	1.7435	
2	Top conductor	Silver	0.3805	Silver	7440-22-4	100	1.545	1.545
3	Bottom conductor	Silver	0.1948	Silver	7440-22-4	100	0.791	0.791
4	Resistor	Ruthenium Oxide	0.2361	Palladium	7440-05-3	40	0.383	0.959
				Silver	7440-22-4	35	0.336	
				Ruthenium(IV) oxide	12036-10-1	15	0.144	
				Silicon dioxide	14808-60-7	10	0.096	
5	First encapsulating	Glass	0.2277	Glass	65997-17-3	92	0.851	0.925
				Chromium(III) oxide	1308-38-9	8	0.074	
6	Overcoat	Resin	0.5224	Resin	25036-25-3	100	2.121	2.121
7	Side conductor	Silver	0.5031	Silver	7440-22-4	85	1.736	2.042
				Resin	9003-36-5	15	0.306	
8	Plating (Middle)	Nickel	0.4246	Nickel	7440-02-0	100	1.724	1.724
9	Plating (Outer)	Tin	0.6370	Tin	7440-31-5	100	2.587	2.587
10	Marking	Resin	0.0324	Resin	29690-82-2	70	0.092	0.131
				Titanium oxide	1317-80-2	30	0.039	
Total weight			24.6272					

This Document was updated on: 09/01/2016

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.